

A CURABLE POLYPHENYLENE ETHER-THERMOSETTING RESIN
COMPOSITION AND PROCESS

ABSTRACT

5 Polyphenylene ether-thermosetting resin compositions are provided that are useful as dielectrics, particularly printed circuit boards having improved processability, good solvent and solder resistance, as well as improved morphology as compared to other polyphenylene ether-thermosetting resin compositions. More specifically, the particular polyphenylene ether resin component of this invention has a molecular weight of less than about 3,000 number average in contrast to higher molecular weight polyphenylene ethers employed in other polyphenylene ether-thermosetting resin compositions for use in preparing printed circuit boards.